

9-28-01  
09967074

ASSIGNMENT RECORDATION COVER SHEET  
-PATENTS ONLY-

Jc872 U.S. PTO  
09/967074  
09/28/01

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)

- a) Helmut Puchner  
b) Ming-Yi Lee  
c)

10-11-2001



101872262

2. Name and address of receiving party(ies):

- a) Name: LSI Logic Corporation  
Address: 1551 McCarthy Boulevard  
Milpitas, California 95035

3. Nature of conveyance

- |  |  |
|--|--|
| <input checked="" type="checkbox"/> Assignment | <input type="checkbox"/> Merger            |
| <input type="checkbox"/> Security Agreement    | <input type="checkbox"/> Change of Name    |
| <input type="checkbox"/> Other                 | <input type="checkbox"/> License Agreement |

Execution Date: September 25, 2001

4. Application Number(s) or Patent Number(s): Please assign

The title of the (new) application is:

FABRICATION OF METAL CONTACTS FOR DEEP-SUBMICRON TECHNOLOGIES

5. Please send all correspondence concerning this (these) documents to:

**Customer Number: 24319**

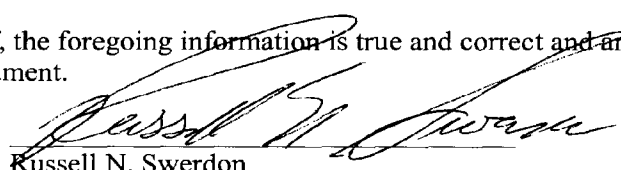
6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☐ Enclosed  
☒ Any fees are authorized to be charged to Deposit Account No. 12-2252 (Order No. 01-357)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: September 28, 2001

  
Russell N. Swerdon  
Registration No. 36,943

Attorney Docket No. LSI1P176/01-568

(Revised 01/96)

**PATENT**  
**REEL: 012228 FRAME: 0748**

**ASSIGNMENT**

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the undersigned, Hong-Qiang Lu, Wei-Jen Hsia and Wilbur G. Catabay, does hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

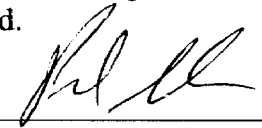
( X ) which has been executed by the undersigned concurrently herewith,  
 ( ) which was filed on \_\_\_\_\_, 20\_\_\_\_ and assigned Application No. \_\_\_\_\_,


and is entitled: **FABRICATION OF METAL CONTACTS FOR DEEP-SUBMICRON TECHNOLOGIES**

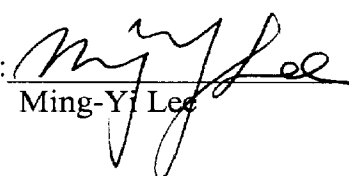
and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

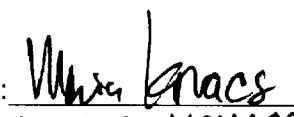
Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name:   
 Helmut Puchner

Date: Sep 25, 2001 Witness:   
 Printed Mark Salvatore

Name:   
 Ming-Yi Lee

Date: Sep. 25, 2001 Witness:   
 Printed MARIA KOVACS

LSI Logic Corporation  
 Intellectual Property  
 Corporate Legal Department  
 1551 McCarthy Blvd., MS D-106  
 Milpitas, California 95035  
**PATENT**